

JICO

- Boat made of same ultra pure material as the wafer.
- Similar Thermal Expansion Coefficient.
- Very low cost of ownership.
- Significant particle reduction.
- Very low maintenance cost.
- High furnace uptime.
- High temperature process capability.
- Thick film deposition capability.
- Common cleaning processes in Semiconductor Industry shows no impact to the welding area.
- Best uniformity (batch to batch 0.09% deviation)

	SILICON	QUARTZ	SIC
DIVITRIFICATION	NO	YES	NO
1200 TO 1380	STABLE	PLASTIC, WARPS	STABLE
CO-EFFICIENT OF THERMAL EXPANSION	SIMILAR TO WAFER	~5 TIMES LESS	~1.85 TIMES MORE
THERMAL CONDUCTIVITY (1000DEGC)	SIMILAR TO WAFER	~10 TIMES HIGHER	~10% LESS
ESTIMATED COSTS OF OWNERSHIP (ANNUALLY)	100%	~380%	~195%
SLIP AT 1200DEGC	NONE	N.A.	YES
Purity	0.35	4.1	1.45

